# Compact Momentary Type

# Two poles and two contact points, Comfortable momentary operation with click feel







## ■ Typical Specifications

Ite	ms	Specifications		
Rating (max.) (Resistive load)		0.2A 14V DC		
Contact resistand (Initial/After opera	-	150m $\Omega$ max. / 150m $\Omega$ max.		
Operating forces		3.5±0.7N		
Operating life	Without load	10,000 cycles		
Operating life	With load	10,000 cycles (0.2A 14V DC)		

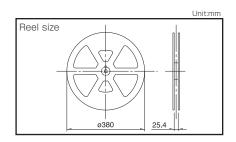
#### Product Line

Travel (mm)	Poles	Positions	Minimum order unit (pcs.)		Product No.
			Japan	Export	Product No.
1.7	2	2	500	2,000	SPEJ110100

#### Packing Specifications

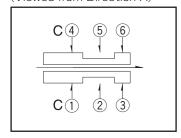
### Taping

Nun	nber of packages (p	Tape width	Export package measurements		
1 reel	1 case /Japan	1 case /export packing	(mm)	(mm)	
500	1,000	2,000	24	404×397×140	

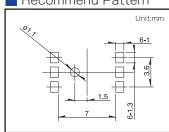


# Dimensions Unit:mm Style Terminal No.1-2 and Terminal No.4-5 Turnover position Terminal No.①-③ and Terminal No.④-⑥ Turnover position Full Stroke Position 2.9 6 7.5 0 0 Terminal No.4 ø0.9 Terminal No.① Terminal No. 5 Terminal No.6 Terminal No.② Terminal No.3

## Circuit Diagram (Viewed from Direction A)



### Recommend Pattern



On its			Vertical						
Series		SPEH	SPEG	SPEJ	SPPH2	SPPH4	SPPH1		
	Photo								
		W	6	7.19	7	6	6.5	10	
Dimensio (mm)		D	6	8.39	7	6.5	8.5	10	
		Н	5	3.5	5.95	6.5 8.5		.5	
Tra	vel (mm)	)	_	_	1.7	1	2.2	1.5	
Total	travel (m	ım)	1.6	1.1	1.7	1.5	3	2.5	
Numb	per of pol	es	1	1	2		2		
	perating rature ra	nge	-40℃ to +90℃	-10°C to +60°C	-40℃ to +85℃		-10°C to +60°C		
Auto	motive u	se	•	_	•	_	_	•	
Li	fe cycle		<b>*</b> 3	<b>*</b> 3	*3	<b>★</b> 3 <b>★</b> 3 <b>★</b> 3		<b>*</b> 3	
	ng (max istive loa		50mA 16V DC	1mA 5V DC	0.2A 14V DC	0.1A 12V DC 0.1A 30V DC		OV DC	
	ing (min. istive loa		10μA 1V DC	50μA 3V DC	_	50μA 3V DC			
D. white		ting life ut load	100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.	
Durability		life with load rated load)	100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.	
		contact tance	200mΩ max.	200mΩ max.	150mΩ max.	30mΩ max. 100mΩ max. 20mΩ		20mΩ max.	
Electrical performance		lation tance	100MΩ min. 100V DC	3MΩ min. 100V DC	100MΩ min. 500V DC	100MΩ min. 500V DC		)C	
	Voltag	ge proof	250V AC for 1minute	100V AC for 1minute	500V AC for 1minute	500V AC for 1minute		е	
		minal ength	_	0.5N for 1minute	_	5N for 1minute			
Mechanical performance	Mechanical Operatin		50	DN	49N	30N 50		50N	
	strength		_	_	_	_	10N	_	
	Cold		-40°C 1,000h	-20°C 96h	-40℃ 500h	-20°C 96h			
Environmental performance	Dry heat		90°C 1,000h	85℃ 96h	85°C 500h	85°C 96h			
	Damı	o heat	60°C, 90 to 95% RH 1,000h	40°C, 90 to 95% RH 96h	60°C, 90 to 95% RH 500h	40°C, 90 to 95%RH 96h			
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#### Note

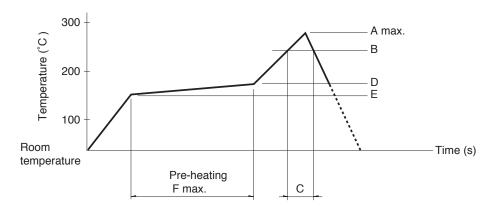
• Indicates applicability to all products in the series.



# Push Switches Soldering Conditions

### Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
- 3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)
SPEG						
SPEJ	260	230	40	180	150	120
SPEF						
SPEH						

#### Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

#### Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10°C	4s max.	
SPEG, SPEF	350±5℃	3s max.	
SPEH, SPPH2	350°C max.	3s max.	
SPUJ	300±10°C	3+1/0s	

#### Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

